PATENT COOPERATION TREATY

PCT

REC'D 1	1 NOV 2004
WIPO	PCT

INTERNATIONAL PRELIMINARY REPORTON PATENTABILITY

(Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference	Top yarden i car	<u></u>		
FP0301PCTMES	FOR FURTHER ACTION	ON .	See Form PCT/IPEA/416	.
International application No. PCT/JP 03 / 08312	International filing date (da	• • •	Priority date (day/month/y	ear)
	30.06.		11.07.2	002
International Patent Classification (IPC)	or national classification and	d IPC		
Int.Cl ⁷	01/00F G00D00/	'26 - 602 7 00	10.5	
H01L21/02, H01L2	41/205,C03B29/	36, C03B29	/06	
Applicant		<u> </u>	<u> </u>	
	NG & SHIPBU	TIDING CO	TUT	
MIIDOI DIGINGERI	NG & SHIPBU.	TIDING CO	LTD.	
This report is the international p Authority under Article 35 and tr	oreliminary examination re	eport, established by according to Article	y this International Prelimin 36.	ary Examining
2. This REPORT consists of a total	_	cluding this cover sl		
This report is also accompanied t	y ANNEXES, comprising	: .		
a. a total of	sheets, as follows:	•		
sheets of the de	escription, claims and/or dra	awings which have b	een amended and are the bas	is of this report
and/or sheets c Administrative	ontaining rectifications autl	horized by this Auth	ority (see Rule 70.16 and Sec	ction 607 of the
sheets which s	apersede earlier sheets, but	which this Authority	y considers contain an amend	lment that goes
beyond the disc Supplemental I	closure in the international	application as filed,	as indicated in item 4 of Box	No. I and the
b. a total of (indicate type	e and number of electronic	carrier(s))		· · · · · · · · · · · · · · · · · · ·
Supplemental Box Rel	ating to Sequence Listing (ed thereto, in compi (see Section 802 of t	uter readable form only, as i the Administrative Instructio	ndicated in the ns).
4. This report contains indications r	elating to the following iter	ms:		
Box No. I Basis of th	_			
Box No. II Priority	,		•	
	ishment of opinion with re	gard to novelty inve	entive step and industrial app	licability
	ity of invention		material upp	·
Box No. V Reasoned s	statement under Article 35(2) with regard to nove	elty, inventive step or industri	al applicability;
	nd explanations supporting	such statement	•	
	fects in the international app	Nication		
	servations on the internation	•	•	
	· · · · · · · · · · · · · · · · · · ·	nar application		
Date of submission of the demand		Date of completion	n of this report	
12.02.200)4	•	22.10.2004	-
Name and mailing address of the IPEA/J)	Authorized officer	T.	4L 9170
Japan Patent Off	fice '	YOICHI (SHIMA	11 71/0
3-4-3, Kasumigaseki, Chiyoda-ku, To	okyo 100-8915, Japan	Telephone No. +81	1-3-3581-1101 Ext. 6	764

Box No	. I	Basis of the report
1. Wi	th regard	to the language this report is been done
oth	erwise in	to the language, this report is based on the international application in the language in which it was filed, unless
	which	report is based on translations from the original language into the following language h is the language of a translation furnished for the purposes of:
1		international search (under Rules 12.3 and 23.1(b))
		publication of the international application (under Rule 12.4)
		international preliminary examination (under Rules 55.2 and/or 55.3)
	• •	
2. Wit	th regard	to the elements of the international application, this report is based on (replacement sheets which have been
_		on the spouse to an invitation under Article 14 are referred to in Alica and the second to the secon
and	are not a	nnexed to this report):
V	the in	ternational application and the state of the
		ternational application as originally filed/furnished
	the de	escription:
	pages	as originally filed/firmished
	.pages*	
	pages*	received by this Authority on
	the ole	
لبا	the cla	
	pages	as originally filed/furnished
	pages*	as amended (together with any statement) under Article 19
	pages*	received by this Authority on
	pages*	received by this Authority on
	the dra	twings:
	pages	
	pages*	as originally filed/furnished received by this Authority on
	pages*	received by this Authority on received by this Authority on
	a seque	ence listing and/or any related table(s) - see Supplemental Box Relating to Sequence Listing.
		in the sequence Disting.
3.	The am	nendments have resulted in the cancellation of:
		the description pages
	=	the description, pages
	닏'	he claims, Nos.
	L t	he drawings, sheets/figs
	☐ ti	he sequence listing (specify):
	a	any table(s) related to sequence listing (specify):
4. 🗀		
4.	This rep	port has been established as if (some of) the amendments annexed to this report and listed below had not been since they have been considered to go beyond the disclosure as filed.
	(Rule 7	since they have been considered to go beyond the disclosure as filed, as indicated in the Supplemental Box
		he description, pages
	<u>-</u>	no deima N
•		ne claims, Nos.
	∐ th	ne drawings, sheets/figs
		ne sequence listing (specify):
	ar	ny tahle(s) related to convene listing (
If item 4		some or all of those sheets may be marked "superseded."
		some of all of those sheets may be marked "superseded."

1. Statement			<u> </u>
Novelty (N)	. Claims	1-5	YES
· · · · · · · · · · · · · · · · · · ·	Claims		NO
Inventive step (IS)	Claims	· · · · · · · · · · · · · · · · · · ·	YES
	Claims	1-5	ио
Industrial applicability (IA)	Claims	1-5	YES
•	Claims	* , .	NO

2. Citations and explanations (Rule 70.7)

The following documents have been considered for the purpose of this report:

D1. EP 916750 A1(NIPPON PILLAR PACKING CO., LTD.)1999.05,19 D2. JP 10-55975 A(HITACHI, CO., LTD.)1998.02.24

The subject matter of claim 1-5 does not appear to involve an inventive step in view of the document 1 cited in the ISR and the document 2 cited in the same.

D1 discloses the purpose to provide the large-diameter SiC wafer. D2 discloses the technical feature of a small-diameter single crystal wafer placed in the center of the wafer, and large-diameter polycrystal wafer manufactured by a CVD method to provide the large-size wafer. The technical feature in D1 and D2 are concerned with mutually related technical field, which is wafer manufacturing. Although D1 does not disclose the technical feature of SiC wafer, both the D1 and D2 have the same purpose, that is providing the large-size wafer.

Therefore, the purpose disclosed in D1 and the technical feature disclosed in D2 could constitute the present invention, which would have been easily conceived by the person skilled in the art.